

HVT_GP MODELS (NHVTGP, PHVTGP)

1. CONDITIONS OF EXTRACTION

- Maturity: Preliminary
- Model parameters extraction based on lot : -
- Geometrical extraction domain:
 - Drawn gate length : $0.18 \geq L \geq 0.06 \mu\text{m}$
 - Drawn transistor width : $10 \geq W \geq 0.12 \mu\text{m}$
- Temperature extraction domain: -40°C to 150°C
- Bias extraction domain:
 - Gate bias: $0 \leq |V_{GS}| \leq 1.1 \text{ V (VDD + 10\%)}$
 - Drain bias: $0 \leq |V_{DS}| \leq 1.1 \text{ V (VDD + 10\%)}$
 - Bulk bias: $0 \leq |V_{BS}| \leq 1.1 \text{ V (VDD + 10\%)}$

2. CONDITIONS OF SIMULATION

- Temperature: 25°C
- Currents:
 - $I_{DLIN} = I_{ds}$ at $V_{gs} = 1.0 \text{ V}$, $V_{ds} = 50 \text{ mV}$ and $V_{bs} = 0 \text{ V}$
 - $I_{ON} = I_{ds}$ at $V_{gs} = 1.0 \text{ V}$, $V_{ds} = 1.0 \text{ V}$ and $V_{bs} = 0 \text{ V}$
 - $I_{OFF} = I_{ds}$ at $V_{gs} = 0 \text{ V}$, $V_{ds} = 1.0 \text{ V}$ and $V_{bs} = 0 \text{ V}$
 - $I_{G_ON} = I_{gs}$ at $V_{gs} = 1.0 \text{ V}$ and $V_d = V_s = V_b = 0 \text{ V}$
 - $I_{G_OFF} = I_{gs}$ at $V_{gs} = V_{bs} = 0 \text{ V}$ and $V_{ds} = 1.0 \text{ V}$
- Threshold voltage in linear and saturation regime
 - V_{TLIN} is V_{gs} value at $V_{ds} = 50 \text{ mV}$, $V_{bs} = 0 \text{ V}$ and $I_{ds} = 40 \cdot W/L \text{ nA}$.
 - V_{TSAT} is V_{gs} value at $V_{ds} = 1.0 \text{ V}$, $V_{bs} = 0 \text{ V}$ and $I_{ds} = 40 \cdot W/L \text{ nA}$.
- Current derivatives:

$$G_m = \frac{\partial}{\partial V_{gs}} I_{ds} \text{ at } V_{gs} = V_{TLIN} + 0.2 \text{ V}, V_{ds} = 0.5 \text{ V and } V_{bs} = 0 \text{ V}$$

$$G_d = \frac{\partial}{\partial V_{ds}} I_{ds} \text{ at } V_{gs} = V_{TLIN} + 0.2 \text{ V}, V_{ds} = 0.5 \text{ V and } V_{bs} = 0 \text{ V}$$

$$\text{Analog gain} = G_m/G_d$$

- Gate Capacitances:

CGGINV = CGG at $V_{gs} = 1.0 \text{ V}$, $V_{ds} = 0 \text{ V}$ and $V_{bs} = 0 \text{ V}$

CGD_0V = CGD at $V_{gs} = 0 \text{ V}$, $V_{ds} = 0 \text{ V}$ and $V_{bs} = 0 \text{ V}$

$$CGGMEAN = \frac{1}{VDD} \cdot \int_0^{VDD} CGG \times dV_{gs} \text{ with } VDD = 1.0 \text{ V and } V_{bs} = 0 \text{ V}$$

TAU = CGGMEAN*VDD/ION

- Diode Capacitances:

CBD OFF = CBD at $V_{gs} = 0 \text{ V}$, $V_{ds} = 1.0 \text{ V}$ and $V_{bs} = 0 \text{ V}$

Note: the area and perimeters of source/drain junction diodes used for simulation are defined with the the minimum poly-to-active distance specified in the DRM.

- Transition frequency:

FT = frequency for which the small signal current gain H_{21} is 0 dB (i.e. $\left| \frac{I_d}{I_g} \right| = 0 \text{ dB}$).

3. MAIN ELECTRICAL CHARACTERISTICS OF NMOS HVT_GP TRANSISTORS

PARAMETERS	HVTGP_TT	HVTGP_SS	HVTGP_FF	units
N-channel transistors (nhvtgp)				
VTLIN W=1/L=0.18	386	412	360	mV
IDLIN W=1/L=0.18	3.75e-05	3.34e-05	4.19e-05	A
VTSAT W=1/L=0.18	364	390	338	mV
ION W=1/L=0.18	1.78e-04	1.51e-04	2.08e-04	A
VTLIN W=1/L=0.06	350	400	295	mV
IDLIN W=1/L=0.06	1.01e-04	8.60e-05	1.18e-04	A
VTSAT W=1/L=0.06	211	276	137	mV
ION W=1/L=0.06	6.33e-04	5.05e-04	7.88e-04	A
IOFF W=1/L=0.06	5.10e-09	1.23e-09	2.89e-08	A
IG_ON W=1/L=0.06	5.46e-09	2.73e-09	1.11e-08	A
IG_OFF W=1/L=0.06	1.06e-09	5.34e-10	2.12e-09	A
FT W=1/L=0.06	2.94e+11	2.65e+11	3.27e+11	Hz
CGGinv W=1/L=0.06	8.03e-16	8.42e-16	7.61e-16	F
CGGmean W=1/L=0.06	7.60e-16	7.78e-16	7.38e-16	F
CGD 0V W=1/L=0.06	3.37e-16	3.34e-16	3.40e-16	F
CBD OFF ^a W=1/L=0.06	5.14e-16	5.84e-16	4.42e-16	F
Tau W=1/L=0.06	1.2	1.5	0.9	ps
Gm W=1/L=0.06	4.47e-04	3.98e-04	5.07e-04	S
Gd W=1/L=0.06	7.20e-05	5.69e-05	9.30e-05	S
Gain W=1/L=0.06	6.20e+00	6.98e+00	5.46e+00	
VTLIN W=0.12/L=0.06	307	356	253	mV
IDLIN W=0.12/L=0.06	1.39e-05	1.16e-05	1.65e-05	A
VTSAT W=0.12/L=0.06	198	259	131	mV
ION W=0.12/L=0.06	8.89e-05	7.02e-05	1.12e-04	A
IOFF W=0.12/L=0.06	5.65e-10	1.41e-10	3.10e-09	A
FT W=0.12/L=0.06	2.30e+11	2.05e+11	2.61e+11	Hz

Table 1: Main electrical characteristics for NMOS

a. Value corresponding to the minimum poly-to-active distance specified in the DRM

4. MAIN ELECTRICAL CHARACTERISTICS OF PMOS HVT_GP TRANSISTORS

PARAMETERS	HVTGP_TT	HVTGP_SS	HVTGP_FF	units
P-channel transistors (phvtgp)				
VTLIN W=1/L=0.18	315	343	287	mV
IDLIN W=1/L=0.18	1.67e-05	1.49e-05	1.87e-05	A
VTSAT W=1/L=0.18	285	314	257	mV
ION W=1/L=0.18	1.03e-04	8.78e-05	1.21e-04	A
VTLIN W=1/L=0.06	344	390	287	mV
IDLIN W=1/L=0.06	4.03e-05	3.42e-05	4.78e-05	A
VTSAT W=1/L=0.06	229	290	155	mV
ION W=1/L=0.06	3.00e-04	2.35e-04	3.90e-04	A
IOFF W=1/L=0.06	3.07e-09	8.74e-10	1.78e-08	A
IG_ON W=1/L=0.06	3.95e-09	1.88e-09	8.54e-09	A
IG_OFF W=1/L=0.06	1.04e-09	5.17e-10	2.10e-09	A
FT W=1/L=0.06	1.33e+11	1.09e+11	1.62e+11	Hz
CGGinv W=1/L=0.06	8.31e-16	9.03e-16	7.68e-16	F
CGGmean W=1/L=0.06	7.82e-16	8.22e-16	7.48e-16	F
CGD 0V W=1/L=0.06	3.26e-16	3.23e-16	3.28e-16	F
CBD OFF ^a W=1/L=0.06	5.19e-16	5.90e-16	4.45e-16	F
Tau W=1/L=0.06	2.6	3.5	1.9	ps
Gm W=1/L=0.06	2.54e-04	2.26e-04	2.87e-04	S
Gd W=1/L=0.06	3.22e-05	2.44e-05	4.40e-05	S
Gain W=1/L=0.06	7.90e+00	9.24e+00	6.52e+00	
VTLIN W=0.12/L=0.06	264	314	206	mV
IDLIN W=0.12/L=0.06	6.31e-06	5.26e-06	7.62e-06	A
VTSAT W=0.12/L=0.06	179	237	109	mV
ION W=0.12/L=0.06	5.00e-05	3.86e-05	6.57e-05	A
IOFF W=0.12/L=0.06	6.08e-10	1.62e-10	3.68e-09	A
FT W=0.12/L=0.06	9.89e+10	8.18e+10	1.13e+11	Hz

Table 2: Main electrical characteristics for PMOS

a. Value corresponding to the minimum poly-to-active distance specified in the DRM

5. ION, IOFF, VT BEHAVIOR VERSUS GATE LENGTH AND CHANNEL WIDTH FOR NMOS HVT_GP TRANSISTORS

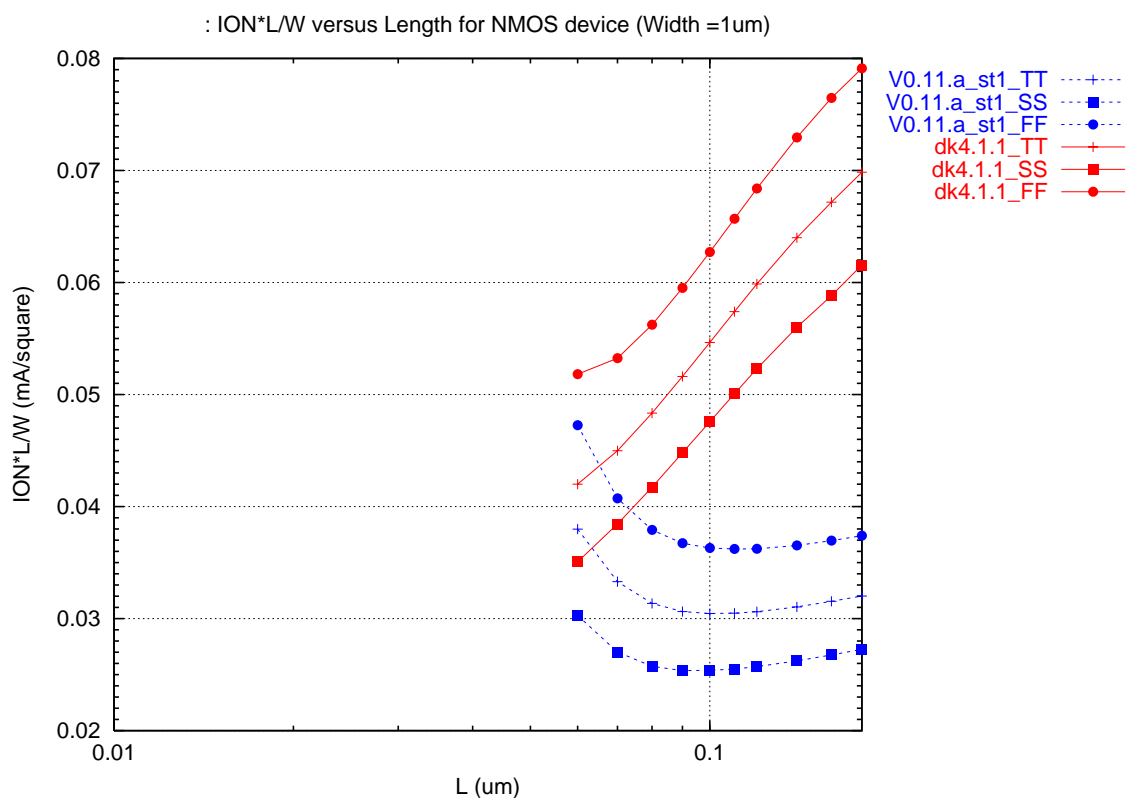


Figure 1 : $ION/\square = ION \cdot L/W$ versus drawn gate length for NMOS HVT_GP transistors ($W = 1 \mu m$)

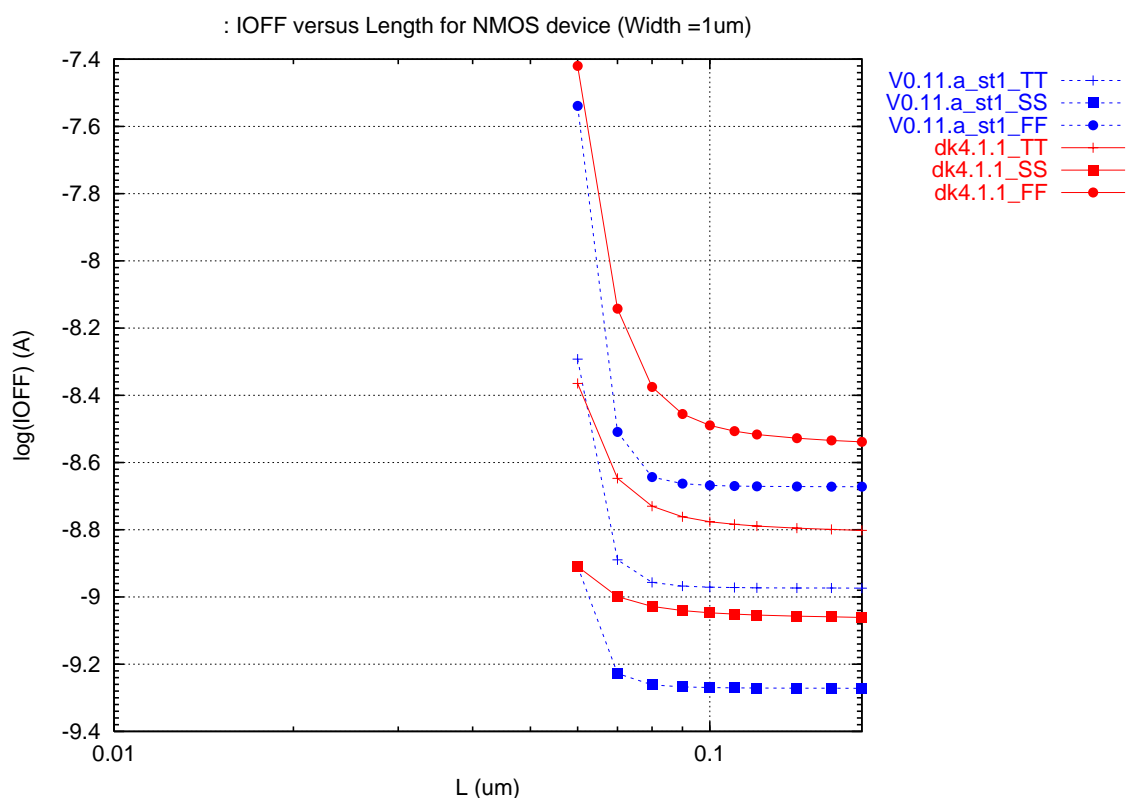


Figure 2 : IOFF versus drawn gate length for NMOS HVT_GP transistors ($W = 1 \mu m$)

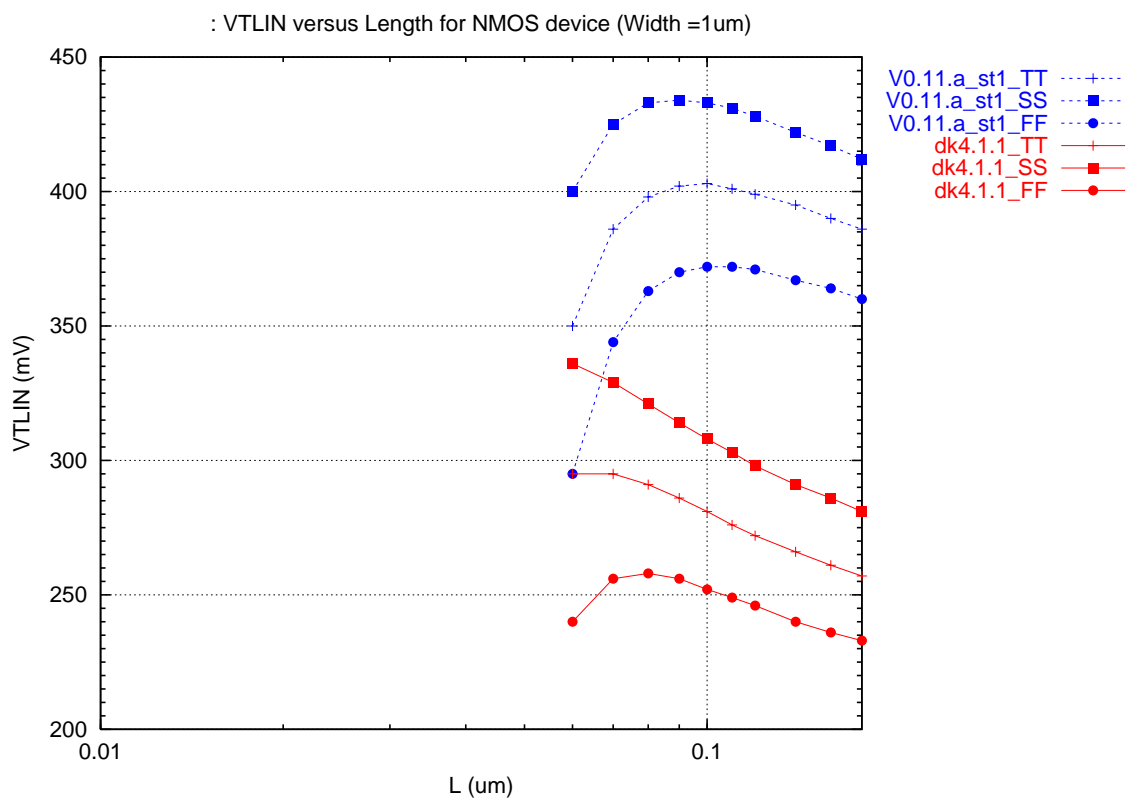


Figure 3 : Threshold voltage VTLIN versus drawn gate length for NMOS HVT_GP transistors ($W = 1 \mu\text{m}$)

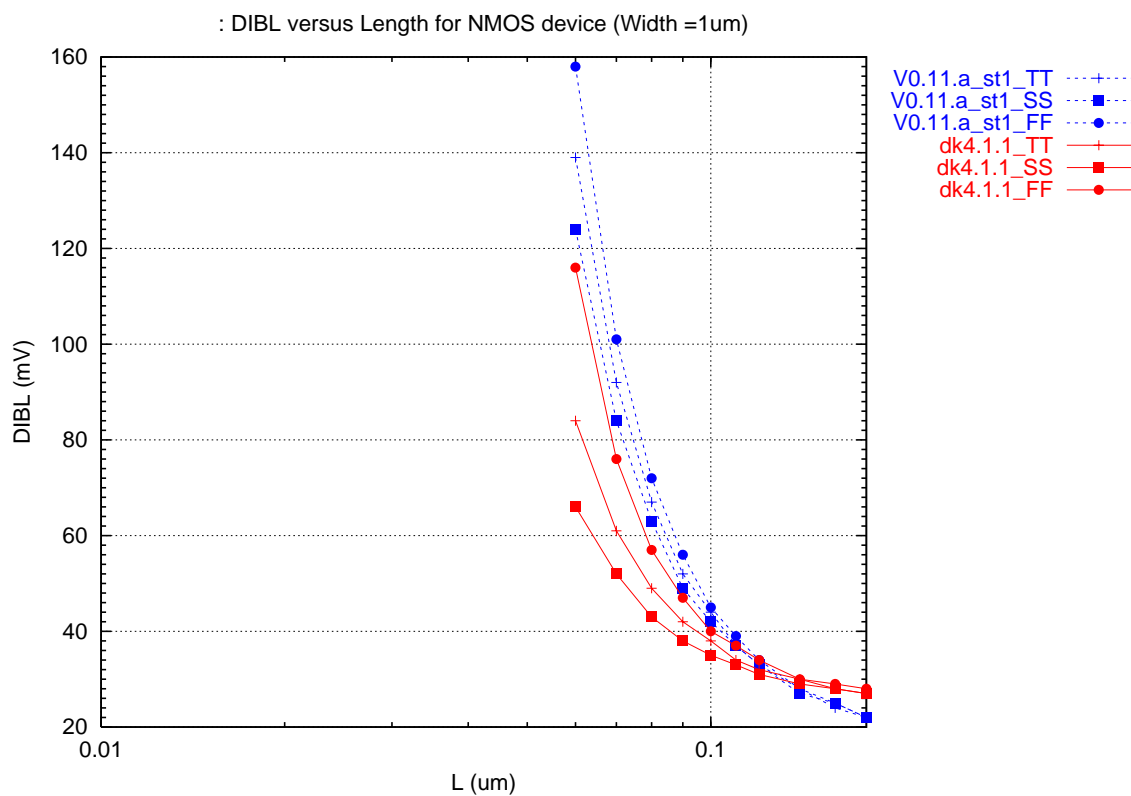


Figure 4 : DIBL= VTLIN-VTSAT versus drawn gate length for NMOS HVT_GP transistors ($W = 1 \mu\text{m}$)

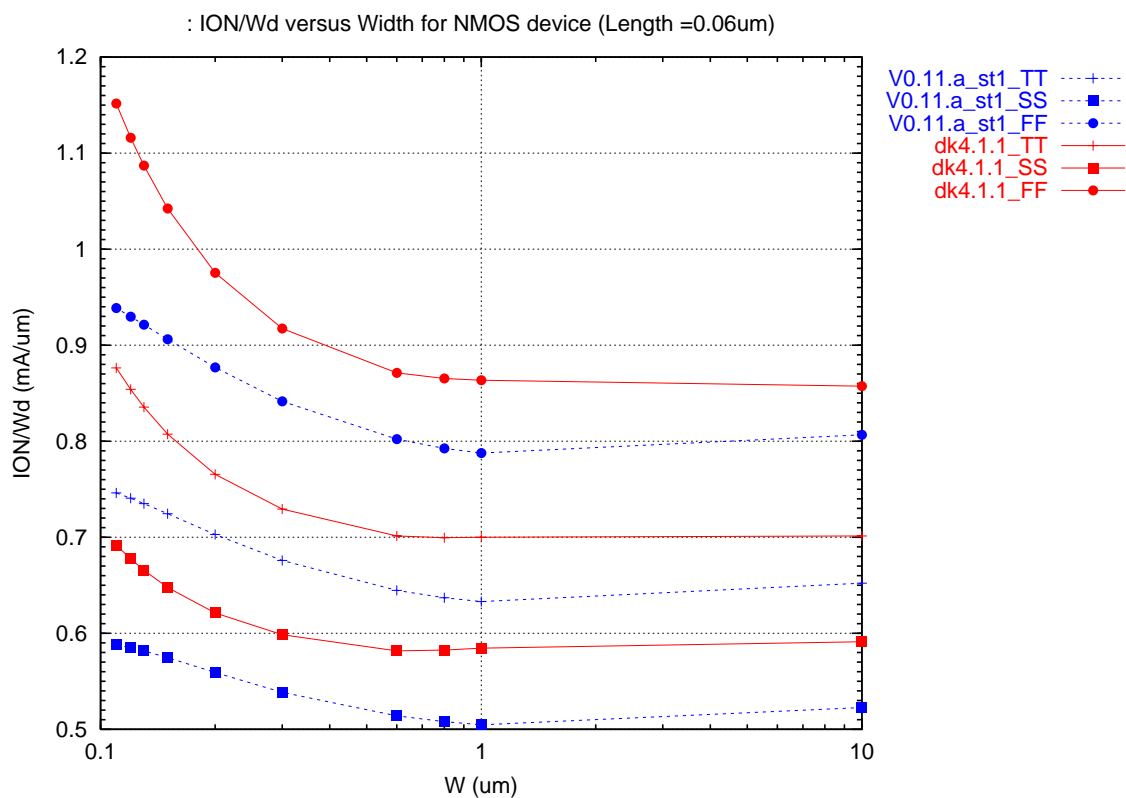


Figure 5 : ION versus drawn channel width for NMOS HVT_GP transistors (L = 0.06 μm)

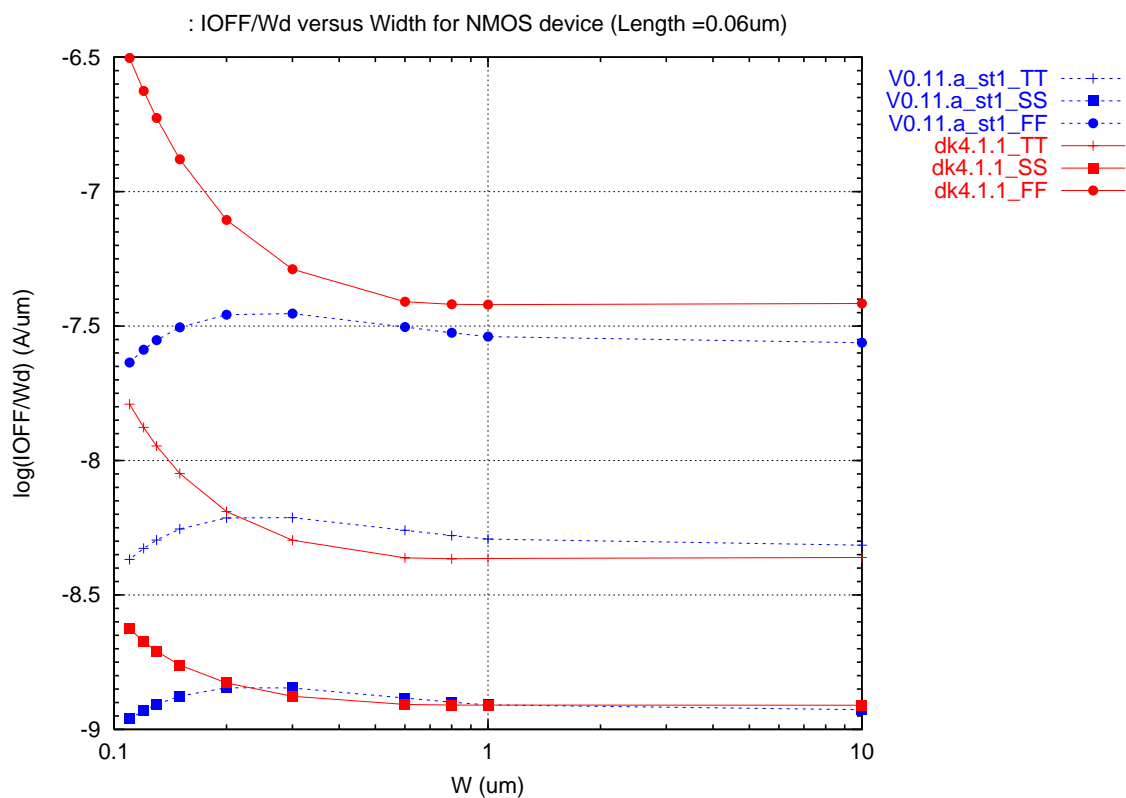


Figure 6 : IOFF versus drawn channel width for NMOS HVT_GP transistors (L = 0.06 μm)

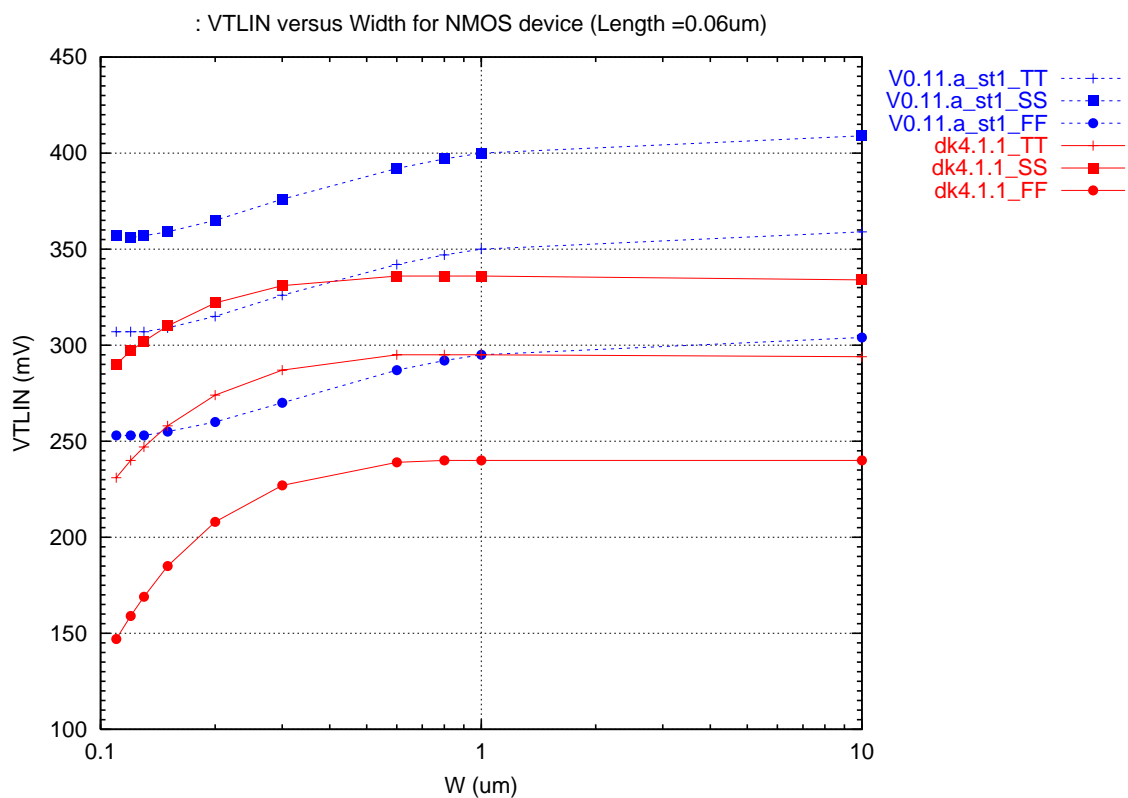


Figure 7 : Threshold voltage VTLIN versus drawn channel width for NMOS HVT_GP transistors ($L = 0.06 \mu\text{m}$)

6. ION, IOFF, VT BEHAVIOR VERSUS GATE LENGTH AND CHANNEL WIDTH FOR PMOS HVT_GP TRANSISTORS

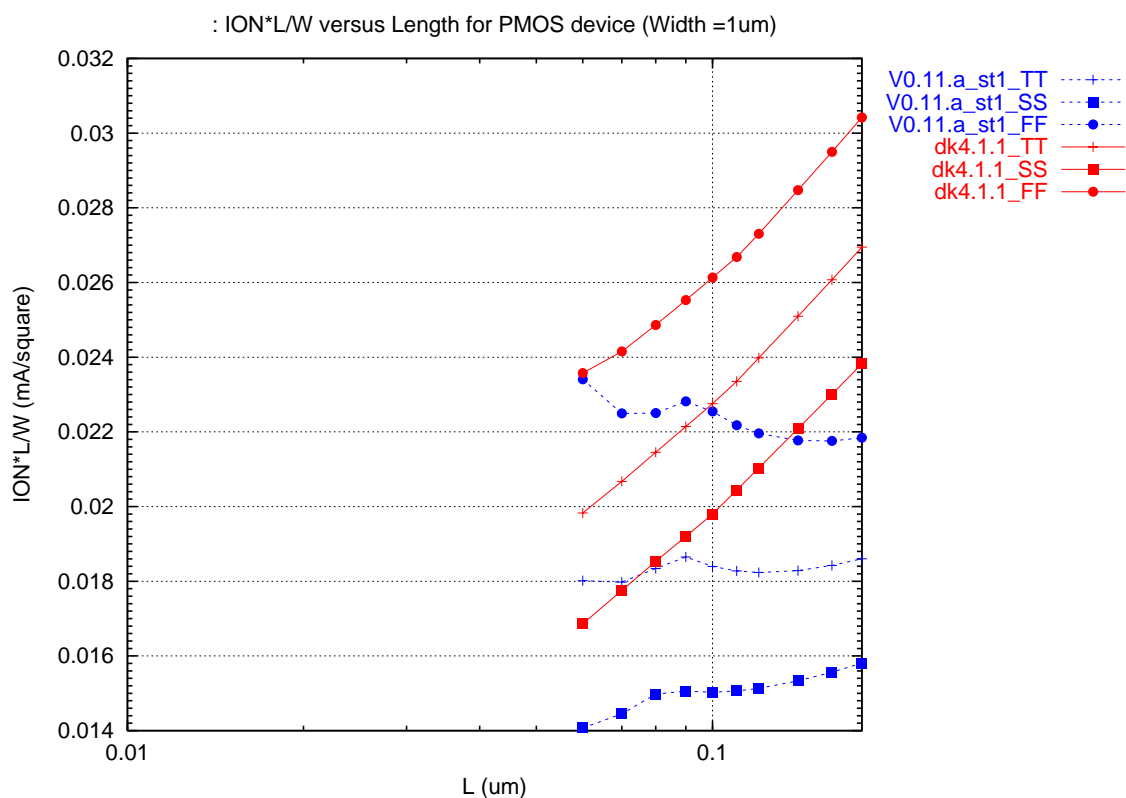


Figure 8 : ION versus drawn gate length for PMOS HVT_GP transistors (W = 1 μ m)

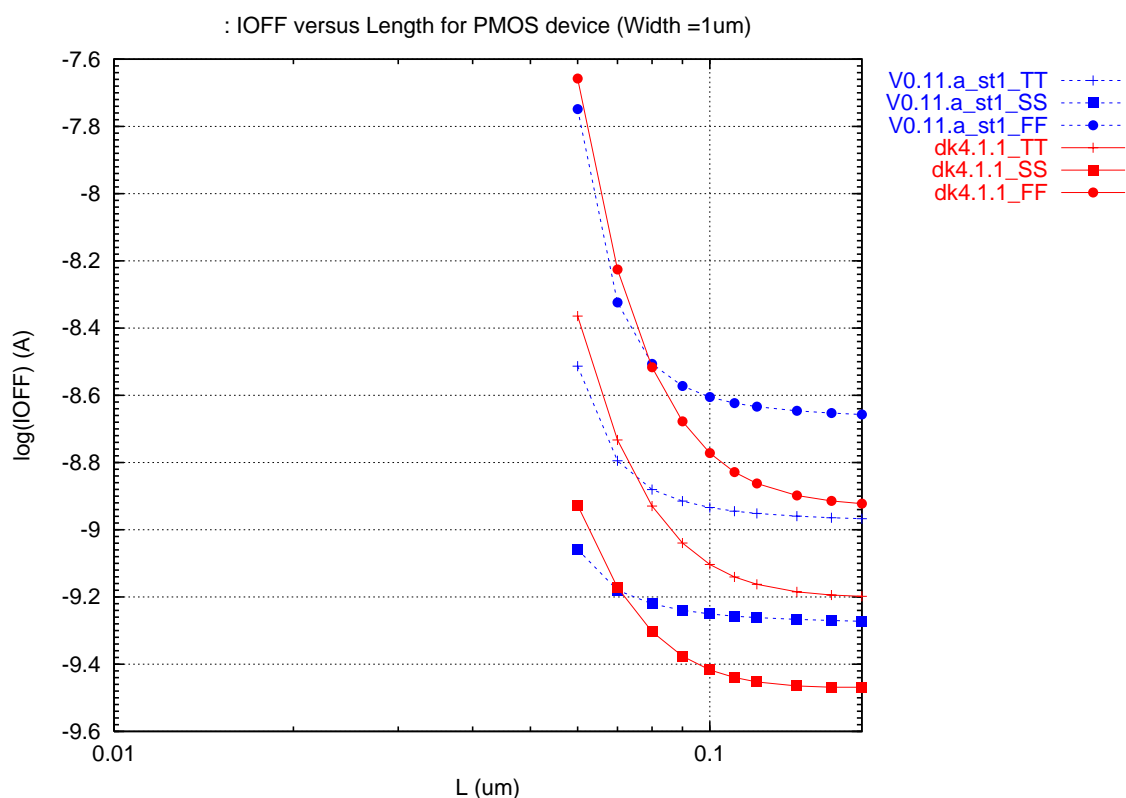


Figure 9 : IOFF versus drawn gate length for PMOS HVT_GP transistors (W = 1 μ m)

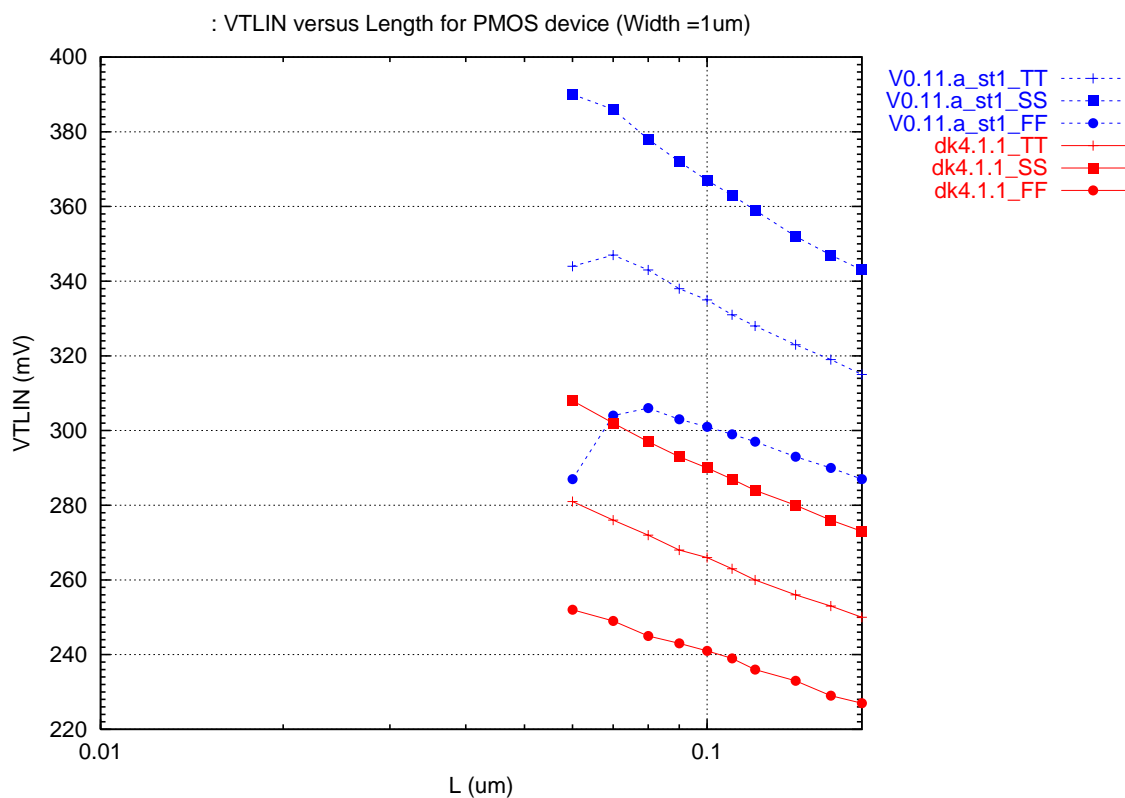


Figure 10 : Threshold voltage VTLIN versus drawn gate length for PMOS HVT_GP transistors ($W = 1 \mu\text{m}$)

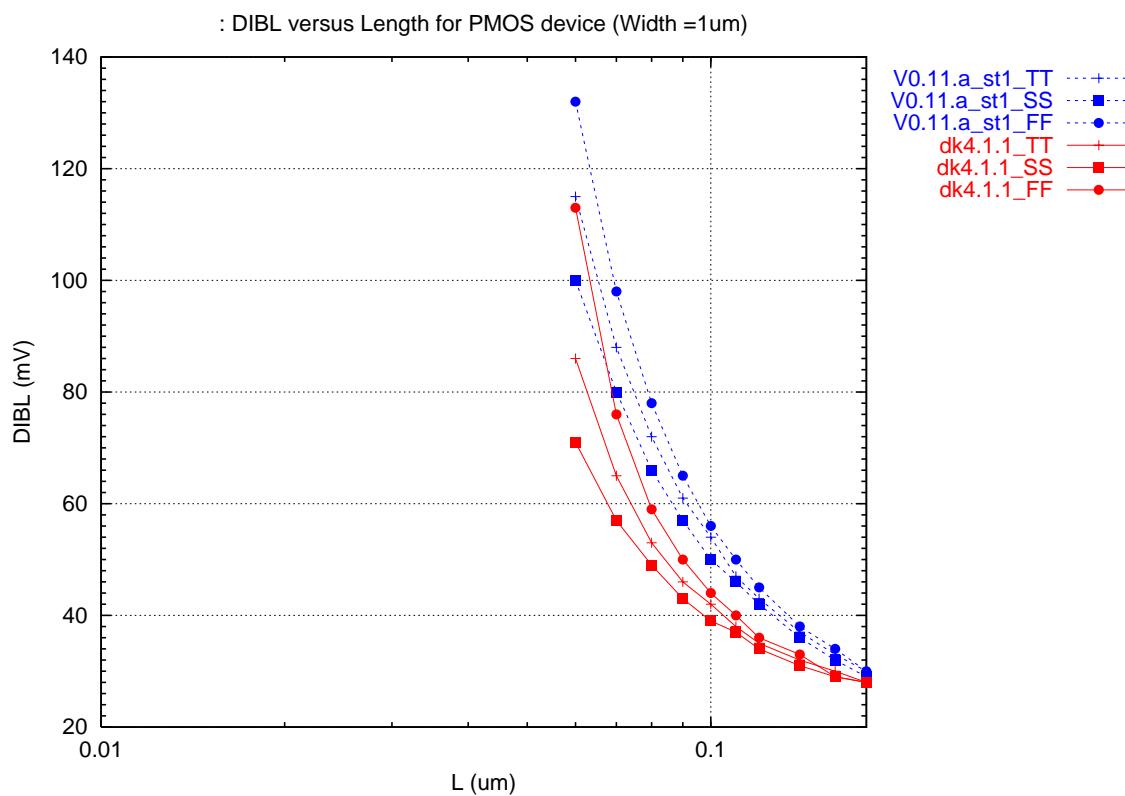


Figure 11 : DIBL= VTLIN-VTSAT versus drawn gate length for PMOS HVT_GP transistors ($W = 1 \mu\text{m}$)

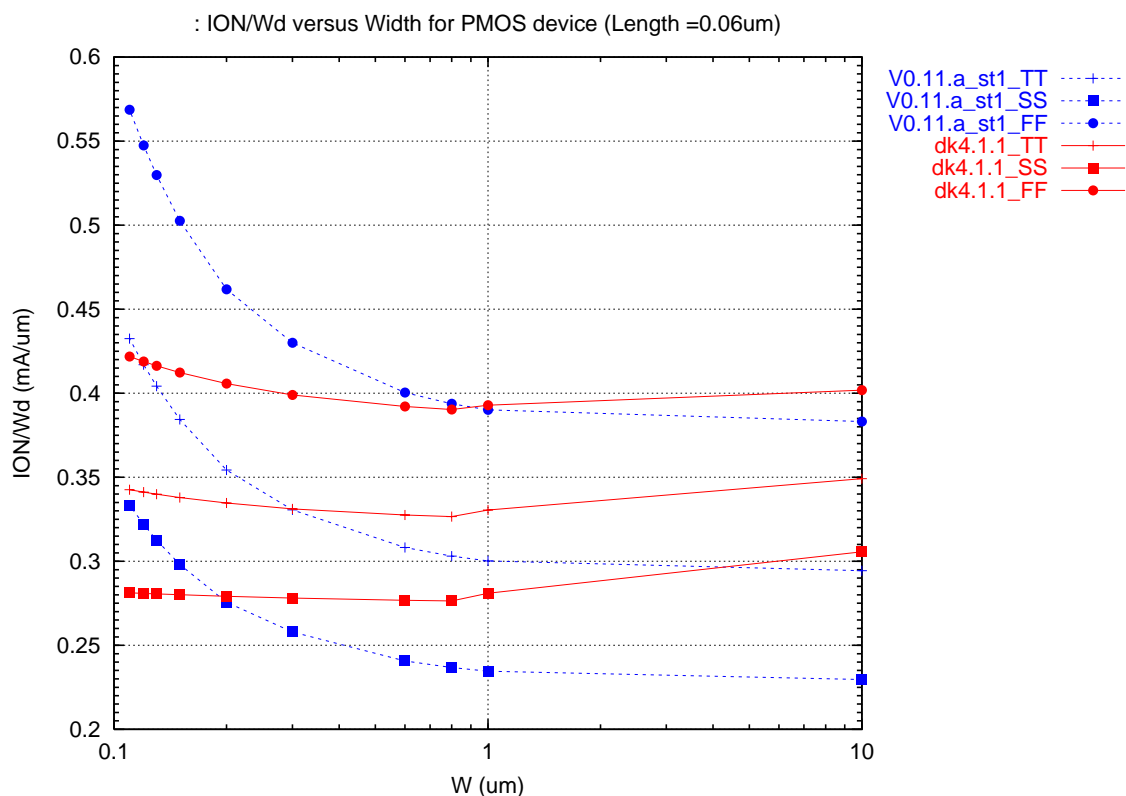


Figure 12 : ION versus drawn channel width for PMOS HVT_GP transistors (L = 0.06 μm)

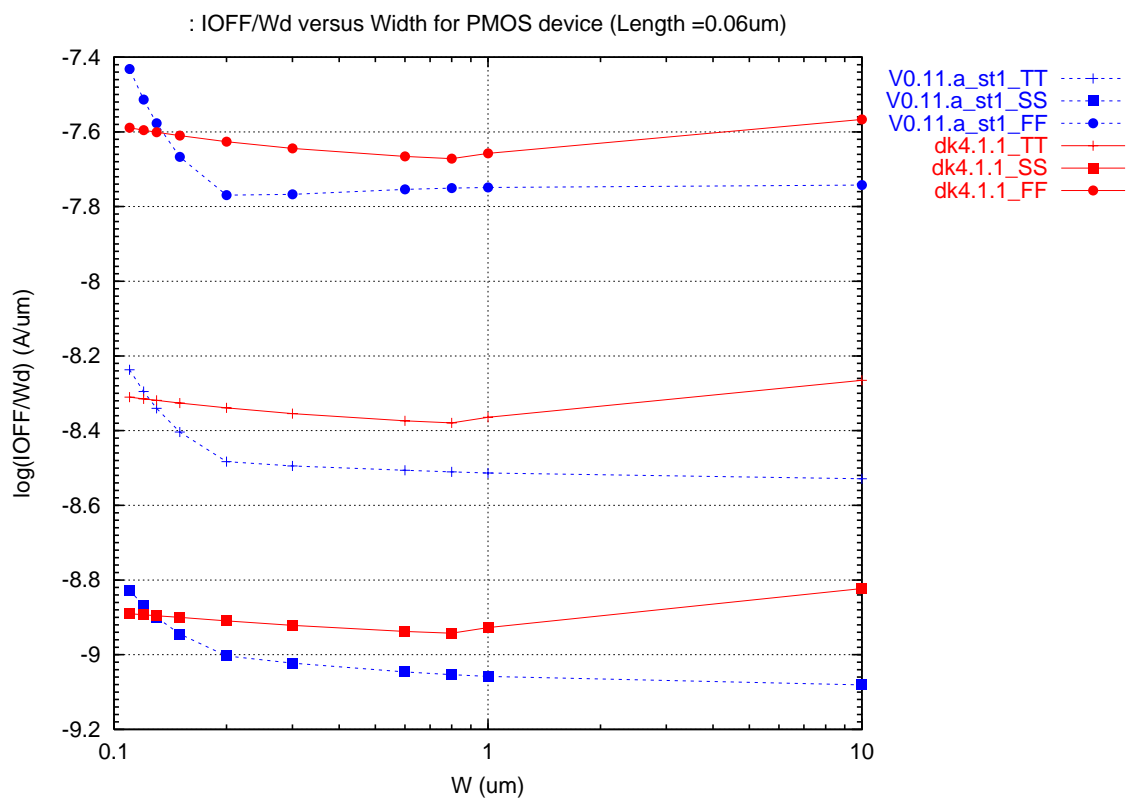


Figure 13 : IOFF versus drawn channel width for PMOS HVT_GP transistors (L = 0.06 μm)

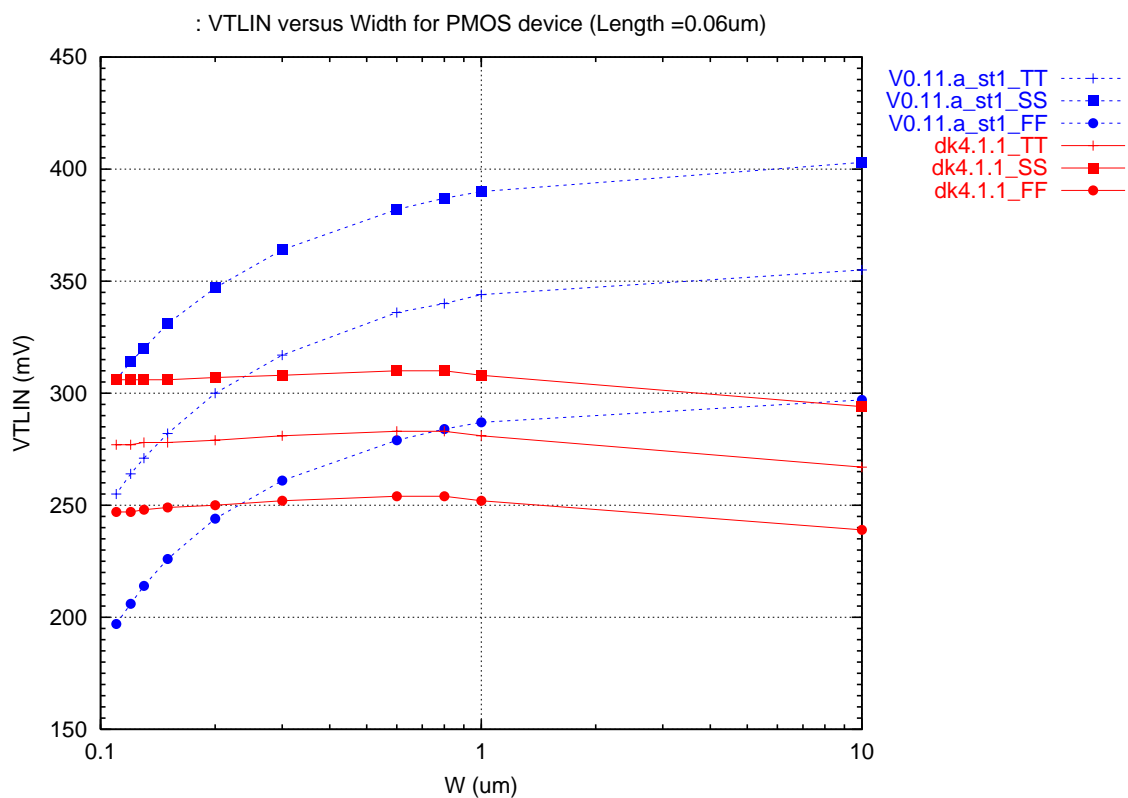


Figure 14 : Threshold voltage VTLIN versus drawn channel width for PMOS HVT_GP transistors (L = 0.06